



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-01-02</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	<b>Giuseppe Vitali Palma</b>	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	F5O7*UQ18BA5	A	BO2A	2014-01-02
Amount	UoM	Unit type	ST ECOPACK Grade	
76.29	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	12	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	F507*UQ188A5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.715	mg	supplier	die	Silicon (Si)	7440-21-3		0.683	mg	955245	8538
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	9790	88
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.006	mg	8392	75
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	1399	13
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.012	mg	16783	150
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.004	mg	5594	50
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	2797	25
Leadframe	Copper & its alloys	37.966	mg	supplier	alloy	Copper (Cu)	7440-50-8		37.87	mg	997471	473375
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.017	mg	448	213
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.032	mg	843	400
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1159	550
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	26	13
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	26	13
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	26	13
Die attach	Other Organic Materials	0.321	mg	supplier	glue	Silver (Ag)	7440-22-4		0.292	mg	909657	3650
Die attach				supplier	glue	acrylate	Proprietary		0.016	mg	49844	200
Die attach				supplier	glue	Methacrylate	Proprietary		0.013	mg	40498	163
Bonding wire	Other inorganic materials	0.163		supplier	wire	Gold (Au)	7440-57-5		0.162	mg	993865	2025
Bonding wire	Other inorganic materials			supplier	wire	Copper (Cu)	7440-50-8		0.001	mg	6135	13
encapsulation	Other Organic Materials	37.125	mg	supplier	mold compound	Epoxy Resin	Proprietary		2.784	mg	74990	34800
encapsulation	Other Organic Materials			supplier	mold compound	Phenol Resin	Proprietary		1.856	mg	49993	23200
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		32.15	mg	865993	401875
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.186	mg	5010	2325
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.149	mg	4013	1863